502212862 01/30/2013

PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yong Liu	03/26/2008
Jeff Ju	03/20/2008
Zhongfa Yuan	03/20/2008
Yongjin (Roger) Luo	03/20/2008

RECEIVING PARTY DATA

Name:	FAIRCHILD SEMICONDUCTOR CORPORATION
Street Address:	82 Running Hill Road
Internal Address:	MS: 35-4E
City:	South Portland
State/Country:	MAINE
Postal Code:	04106

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	7768108

CH $40.00 7768108

CORRESPONDENCE DATA

Fax Number: 5852954401
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: (585) 295-4469
Email: RochesterIP@hblaw.com
Correspondent Name: THOMAS R FITZGERALD
Address Line 1: HISCOCK & BARCLAY, LLP
Address Line 2: 2000 HSBC PLZ., 100 CHESTNUT ST.
Address Line 4: ROCHESTER, NEW YORK 14604

ATTORNEY DOCKET NUMBER:	3059176
NAME OF SUBMITTER:	Thomas R. FitzGerald

Total Attachments: 6
source=2013-01-30-Assignment#page1.tif
source=2013-01-30-Assignment#page2.tif
source=2013-01-30-Assignment#page3.tif
source=2013-01-30-Assignment#page4.tif
source=2013-01-30-Assignment#page5.tif
source=2013-01-30-Assignment#page6.tif

Attorney Docket No.: 018865-028000US
Client Reference No.: 17732.69560.00

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, Yong Liu of 30 Longmeadow Road, Scarborough, ME 04074; Jeff Ju of 81 Quincy Drive, Gorham, ME 04038; Zhongfa Yuan of 1, Sutong Road, China-Singapore Suzhou Industrial Park, Suzhou, Jiangsu, 215021 People's Republic of China; and Roger Luo of 822 Yishan Road, Shanghai , 200030 People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: SEMICONDUCTOR DIE PACKAGE INCLUDING EMBEDDED FLIP CHIP

Date(s) of execution of Declaration:

Filing Date:

Application No.: ; and

WHEREAS, Fairchild Semiconductor Corporation, a corporation of the state of Delaware, located at 82 Running Hill Road, MS 35-4E, South Portland, ME 04106, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: 03/26/2008

Yong Liu
Yong Liu

Dated: 03/20/08

Jeff Ju

Dated: ____________________

Zhongfa Yuan

Dated: ____________________

Roger Luo

61301301 v1

Attorney Docket No.: 018865-028000US
Client Reference No.: 17732.69560.00

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, Yong Liu of 30 Longmeadow Road, Scarborough, ME 04074; Jeff Ju of 81 Quincy Drive, Gorham, ME 04038; Zhongfa Yuan of 1, Sutong Road, China-Singapore Suzhou Industrial Park, Suzhou, Jiangsu, 215021 People's Republic of China; and Roger Luo of 822 Yishan Road, Shanghai , 200030 People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: SEMICONDUCTOR DIE PACKAGE INCLUDING EMBEDDED FLIP CHIP

Date(s) of execution of Declaration:

Filing Date:

Application No.: ; and

WHEREAS, Fairchild Semiconductor Corporation, a corporation of the state of Delaware, located at 82 Running Hill Road, MS 35-4E, South Portland, ME 04106, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: 03/26/2008

Yong Liu
Yong Liu

Dated:____________________ ______________________________
Jeff Ju

Dated: 03/20/2008 Zhongfa Yuan
Zhongfa Yuan

Dated:____________________ ______________________________
Roger Luo

61301301 v1

Attorney Docket No.: 018865-028000US
Client Reference No.: 17732.69560.00

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, Yong Liu of 30 Longmeadow Road, Scarborough, ME 04074; Jeff Ju of 81 Quincy Drive, Gorham, ME 04038; Zhongfa Yuan of 1, Sutong Road, China-Singapore Suzhou Industrial Park, Suzhou, Jiangsu, 215021 People's Republic of China; and Roger Luo of 822 Yishan Road, Shanghai , 200030 People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: SEMICONDUCTOR DIE PACKAGE INCLUDING EMBEDDED FLIP CHIP

Date(s) of execution of Declaration:

Filing Date:

Application No.: ; and

WHEREAS, Fairchild Semiconductor Corporation, a corporation of the state of Delaware, located at 82 Running Hill Road, MS 35-4E, South Portland, ME 04106, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: 03/26/2008

Yong Liu
Yong Liu

Dated: ____________________ ____________________
Jeff Ju

Dated: ____________________ ____________________
Zhongfa Yuan

Dated: 03/20/08 Yongjin (Roger) Luo
Roger Luo

61301301 v1